

	Type	Hits	Search Text
1	BRS	22	257/\$.ccls. and ((encapsulating adj resin) or (encapsulation) or (encapsulating) or (encapsulator)) and ((second adj adhesive) or (adhesive adj layers)) and ((radiating adj fin) or (radiation) or (radiating) or (radiator) or (radiate) or (radiates)) and ((heat adj spreader) or (heat adj sink))
2	BRS	1782	257/712.ccls.
3	IS&R	2	("6184580").PN.
4	BRS	9	257/712.ccls. and (encapsulating adj resin)
5	BRS	853	257/712.ccls.
6	BRS	192	257/\$.CCLS. AND ENCAPSULATING ADJ RESIN
7	IS&R	2	("6184580").PN.
8	BRS	2003	257/\$.ccls. and (adhesive with chip) and (package)
9	BRS	64	257/\$.ccls. and (adhesive with chip with (heat adj spreader)) and (package)
10	BRS	3	257/\$.ccls. and ((adhesive near (heat adj spreader)) with (chip)) and (package)
11	BRS	0	257/\$.ccls. and (chip) and (package) and ((second adj encapsulating adj resin) with (wires))
12	BRS	0	(chip) and (package) and ((second adj encapsulating adj resin) with (wires))
13	BRS	1	(chip) and (package) and ((second adj encapsulating adj resin))
14	BRS	4	(chip) and (package) and ((second adj encapsulating) with (wires))

	DBs	Time Stamp	Comments	Error Definition
1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/30 10:59		
2	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/04/17 14:57		
3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/17 10:52		
4	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/04/17 15:26		
5	JPO	2002/04/17 15:26		
6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/17 15:42		
7	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/17 15:42		
8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/30 11:00		
9	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/30 11:01		
10	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/09/30 11:50		
11	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/09/30 11:53		
12	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/09/30 11:54		
13	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/09/30 11:56		
14	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/09/30 11:57		

	Errors
1	0
2	0
3	0
4	0
5	0
6	0
7	0
8	0
9	0
10	0
11	0
12	0
13	0
14	0